ON Semiconductor®

Initial Product/Process Change Notification

Document # : IPCN22203X
Issue Date: 13 March 2018

Title of Change:	ON Semiconductor is expanding assembly capacity via qualifying external package/assembly subcontractor. Applicable to the family of products (and related OPNs) NCP3230, NCP3231A, NCP3231, NCP3232, NCP3233, NCP3235 and NCP5339.
Proposed first ship date:	10 August 2018 *or earlier upon customer approval.*
Contact information:	Contact your local ON Semiconductor Sales Office.
Samples:	Contact your local ON Semiconductor Sales Office.
Type of notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. IPCNs are issued at least 30 days prior to the issuance of the Final Change Notice (FPCN). An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact <PCN.Support@onsemi.com>.
Change Part Identification:	Parts can be identified through date code marking following ON Semiconductor standards. Contact your local ON Semiconductor Sales Office for the specific date code information.
Change category:	☐ Wafer Fab Change ☒ Assembly Change ☐ Test Change ☐ Other :___________

Change Sub-Category(s):

☒ Manufacturing Site Change/Addition
☐ Manufacturing Process Change
☐ Material Change
☐ Product specific change
☐ Datasheet/Product Doc change
☐ Shipping/Packaging/Marking
☐ Other: ______________________

Sites Affected:	ON Semiconductor Sites: None	External Foundry/Sub con Sites: Advanced Semiconductor Engineering (ASE), Penang, Malaysia

Description and Purpose:

Reason:

ON Semiconductor is expanding the subject products assembly capacity via addition of external assembly subcontractor in the supply chain.

There is no change to the datasheet specifications, or any other aspect of the product.

Item to be changed:	Before Change Description	After Change Description
Addition of Product Assembly Site	ON Semiconductor, Seremban, Malaysia (Internal Assembly Facility)	After the change, Assembly will be done in two locations: 1. ON Semiconductor, Seremban, Malaysia 2. Advanced Semiconductor Engineering (ASE), Penang, Malaysia (subcontractor)

Qualification Plan:

QV Device Name: NCP3231AMNTXG, NCP3235MNTXG, NCP5339MNTXG

Test	Specification	Condition	Interval	Sample Size	# lots
HTOL	JESD22-A108	Ta=125°C, 100 % max rated Vcc	1008 hrs	84	1+control
TC	JESD22-A104	Ta= -65°C to +150°C	500 cyc	84	1+control
HAST	JESD22-A110	130°C, 85% RH, bias	96 hrs	84	1+control
PC	J-STD-020 JESD-A113	MSL 1 @ 85°C/85%RH, 168 Hr 260C reflow All lots prior to HAST, TC	Prior to HAST, TC	All samples	All Qual lots
SAT	J-STD-035	Scanning Acoustic Tomography	Pre and Post PC	5	1
RSH	J-STD-020	Resistance to Solder Heat test		10	1
ED	ON Data Sheet	Electrical Distribution		30	1

Estimated date for qualification completion: 19 April 2018

List of Affected Standard Parts:

Part Numbers	Qualification Vehicle
NCP3230MNTXG	NCP3231AMNTXG NCP3235MNTXG NCP5339MNTXG
NCP3231MNTXG	
NCP3231AMNTXG	
NCP3232NMNTXG	
NCP3233MNTXG	
NCP5339MNTXG	
NCP3235MNTXG	